



REV.	DESCRIPTION	<u>SPECIFICATIONS</u>									
0	Initial design	PROCESS		THICKNESS		COPPER		COSMETICS		MACHINING	
1	Add diode/serial/ant	S/S	-	0.8mm	_	35/00	_	TSMK	X	PANELLISING	X
_	-	D/S	X	1.0mm	_	35/35	X	BSMK	X	V - SCORING	X
_	-	THP	X	1.2mm	_	70/00	_	T-SILK	X	CNC ROUTING	<u> </u>
_	-	NTHP	_	1.6mm	X	70/70	_	B-SILK	X	CUTOUTS	_
_	-	FLASH GOLD	_	2.4mm	-	105	-				

NSB Electronics								
File: BRD009	File: BRD009.kicad_pcb							
Sheet: 1/1	Sheet: 1/1							
Title: Energy	Title: Energy Monitor MCU - DIN							
Size: A4	Date: 12 jan 2016	Rev: 1						
KiCad E.D.A.	pcbnew (2013-07-07 BZR 4022)-stable	ld: 1/1						





